

N-Channel MOSFET

Features:

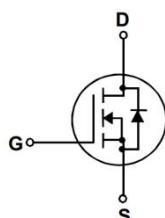
- RoHS Compliant
- Low RDS(on) & FOM
- Excellent stability and uniformity
- Extremely low switching loss
- Peak Current vs Pulse Width Curve

Applications:

- Adaptor
- Charger
- Lighting
- Power Supply

$V_{DSS}(\text{Min.})$	650V
$R_{DS(\text{ON})}(\text{Typ.})$	1.15Ω
I_D	7A

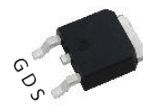
Schematic and Package Information:



TO-220F
CPF07N65A



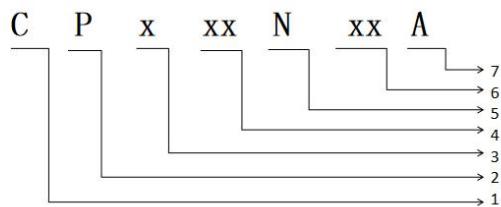
TO-251
CPU07N65A



TO-252
CPD07N65A

Marking on the body:

VD MOSFET tube naming rules



- 1: CYS for short
- 2: P - plane MOS
- 3: Package

F: TO-220F	P: TO-220	D: TO-252
U: TO-251	W: TO-247S/3P	E: SOP-8
G: DFN5*6	K: DFN3.3*3.3	
- 4: Current (above 200V)
- 5: N: N channel P: P channel
- 6: Maximum breakdown voltage (10% of BVdss)
- 7: Series no.

Absolute Maximum Ratings $T_C=25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	CPx07N65A		Units
		TO-220F	TO-251/252	
Drain-to-Source Voltage	V_{DSS}	650		V
Continuous Drain Current	I_D	7		A
Pulsed Drain Current, $V_{GS}@10\text{V}$ (NOTE *1)	I_{DM}	28		A
Power Dissipation	P_D	35	63	W
Derating Factor above 25°C		0.28	0.35	$\text{W}/^\circ\text{C}$
Gate-to-Source Voltage	V_{GS}	± 20		V
Single Pulse Avalanche Energy ($L=10\text{mH}$)	E_{AS}	350		mJ
Peak Diode Recovery dv/dt	dv/dt	5		V/ns
Maximum Temperature for Soldering	T_L	300		$^\circ\text{C}$
Operating Junction and Storage Temperature Range (NOTE *2)	T_J and T_{STG}	150, -55 to 150		

Thermal Resistance

Parameter	Symbol	Typ.		Units
		TO-220F	TO-251/TO-252	
Junction to Case	R _{θJC}	3.57	2.26	°C/W
Junction to Ambient	R _{θJA}	62.5	62	°C/W

Electrical Characteristics TJ=25°C unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Drain-to-Source Breakdown Voltage	BV _{DSS}	650		--	V	V _{GS} =0V, I _D =250μA
Gate Threshold Voltage	V _{GS(TH)}	2	3.3	4	V	V _{DS} =V _{GS} , I _D =250μA
Static Drain-to-Source On-Resistance	R _{DSS(ON)}	--	1.15	1.35	Ω	V _{GS} =10V, I _D =3.5A
Drain-to-Source Leakage Current	I _{DSS}	--	--	1	uA	V _{DS} =650V, V _{GS} =0V T _J =25°C
		--	--	100		V _{DS} =520V, V _{GS} =0V T _J =125°C
Gate-to-Source Forward Leakage	I _{GSS}	--	--	+100	nA	V _{GS} =+30V
Gate-to-Source Reverse Leakage		--	--	-100		V _{GS} = -30V
Forward Transconductance(NOTE *3)	g _f	--	6.5	--	S	V _{DS} =15V, I _D =3.5A

Dynamic Characteristics Essentially independent of operating temperature

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Input Capacitance	C _{iss}	--	1080	--	pF	V _{GS} =0V, V _{DS} =25V f = 1.0MHz
Output Capacitance	C _{oss}	--	90	--		
Reverse Transfer Capacitance	C _{rss}	--	5.9	--		
Total Gate Charge	Q _g	--	22.3	--	nC	ID=7A, VDD=520V VGS = 10V
Gate-to-Source Charge	Q _{gs}	--	5.1	--		
Gate-to-Drain ("Miller") Charge	Q _{gd}	--	9.5	--		
Turn-on Delay Time	t _{d(ON)}	--	19	--		
Rise Time	t _{rise}	--	21	--	ns	V _{DD} =325V, I _D =7A, V _G =10V R _G =10Ω
Turn-Off Delay Time	t _{d(OFF)}	--	42	--		
Fall Time	T _{fall}	--	19	--		

Source-Drain Diode Characteristics T_C=25°C unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
Continuous Drain-Source Diode Forward Current	I _S	--	--	7	A	T _C =25°C
Pulsed Drain-Source Diode Forward Current	I _{SM}	--	--	28		
Diode Forward Voltage	V _{SD}	--	--	1.5	V	I _{SD} =3.5A, V _{GS} =0V I _F = I _S di/dt=100A/us
Reverse Recovery Time	t _{rr}	--	387	--		
Reverse Recovery Charge	Q _{rr}	--	1980	--	nC	

Notes:

1. T_J = +25°C to +150°C.
2. Repetitive rating; pulse width limited by maximum junction temperature.
3. Pulse width < 380μs; duty cycle < 2%.

Typical Characteristics

Figure 1. Typical Output Characteristics

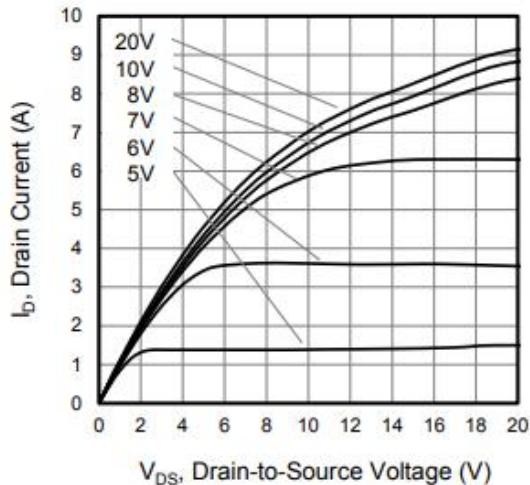


Figure 2. Body Diode Forward Voltage

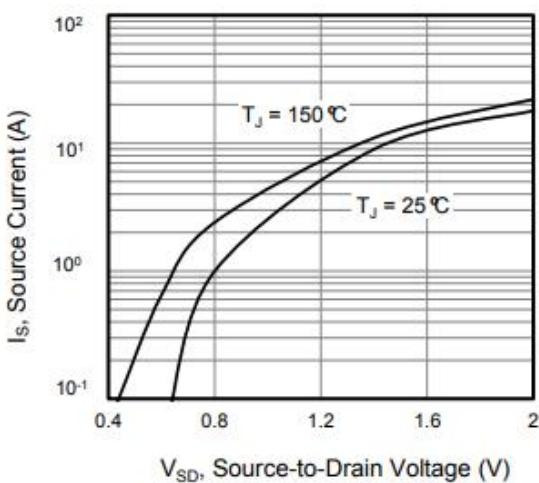


Figure 3. Drain Current vs. Temperature

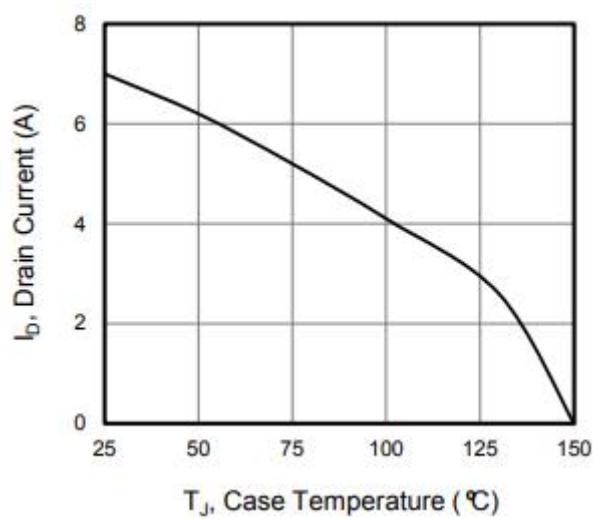


Figure 4. Power Dissipation vs. Temperature

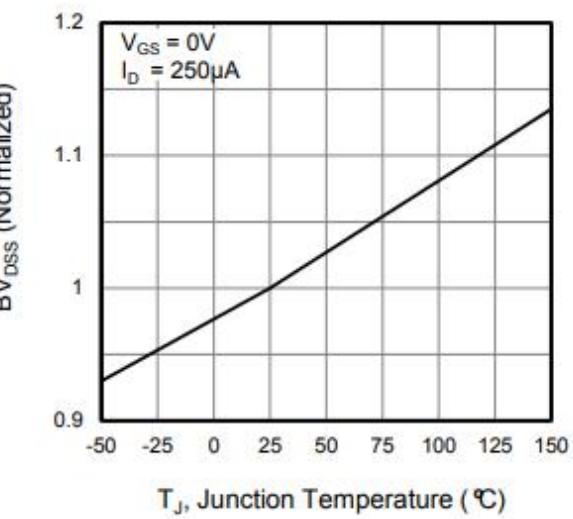


Figure 5. Transfer Characteristics

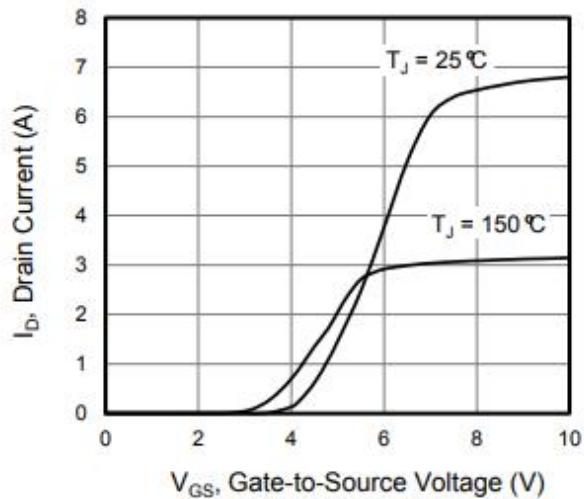


Figure 6. On-Resistance vs. Temperature

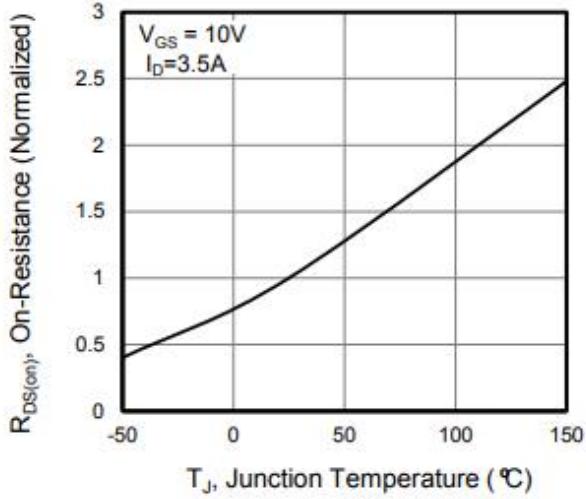


Figure 7. Capacitance

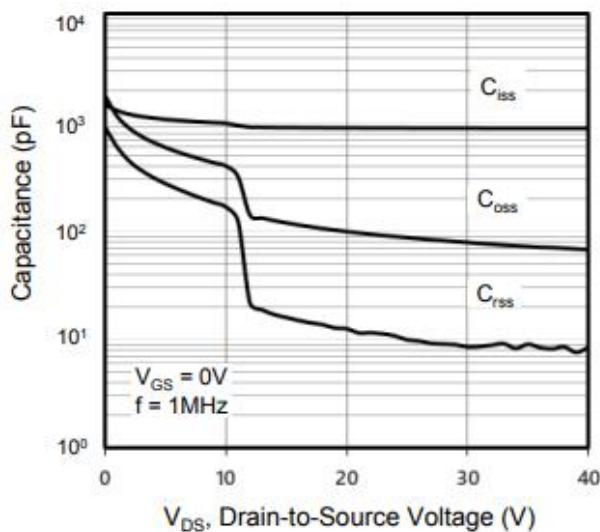


Figure 8. Gate Charge

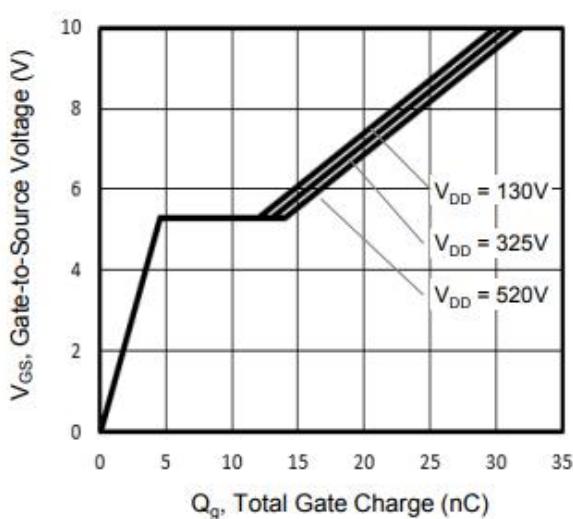


Figure 9. Transient Thermal Impedance

TO-251,TO-252

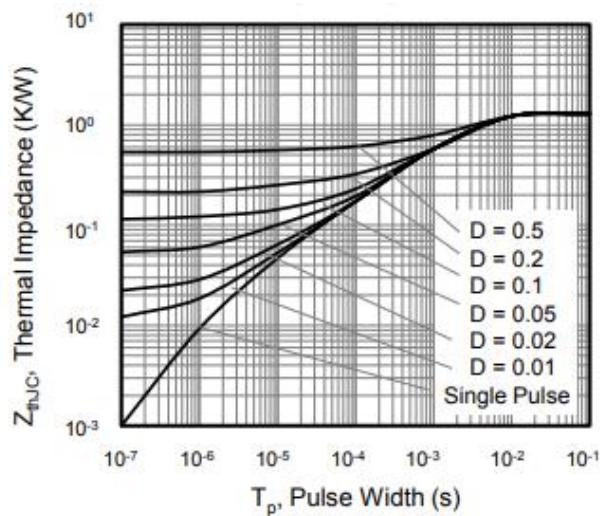
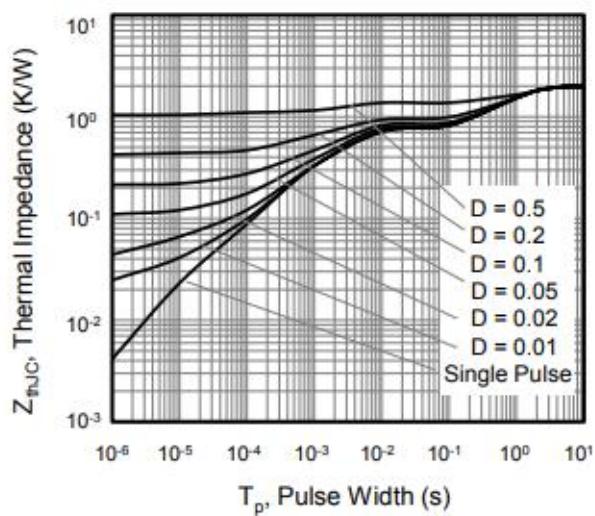
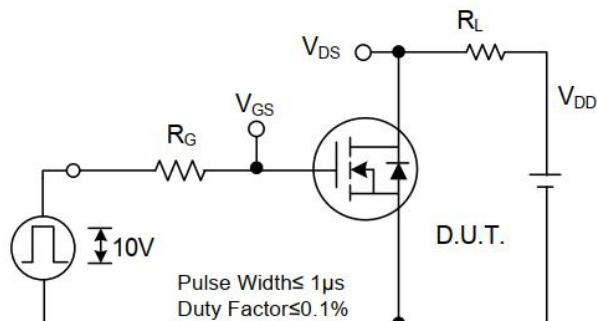


Figure 10. Transient Thermal Impedance

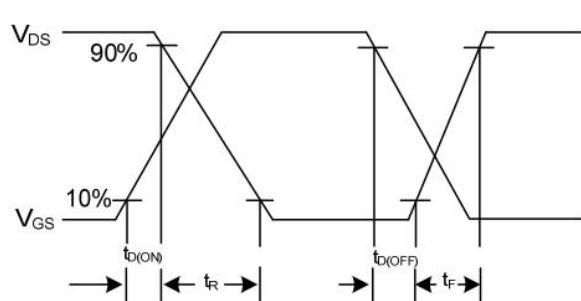
TO-220F



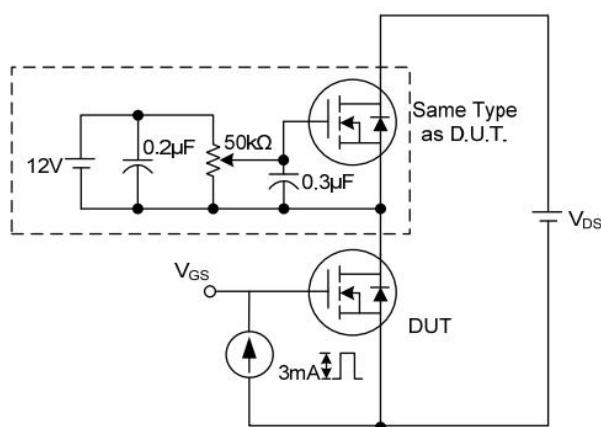
Test Circuits and Waveforms



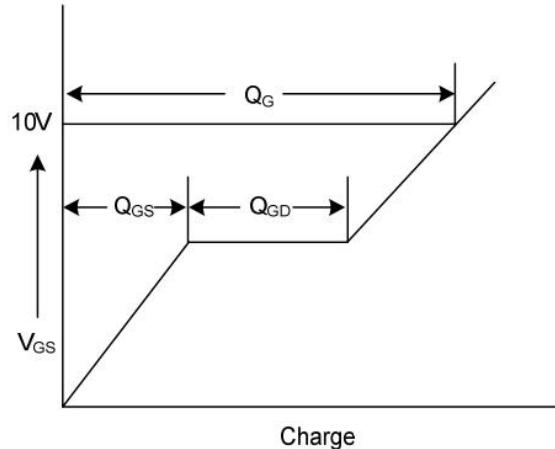
Switching Test Circuit



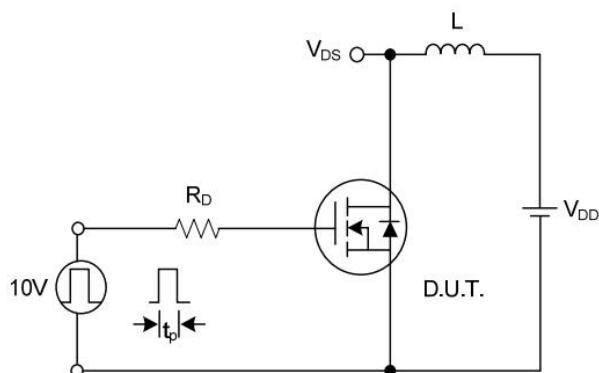
Switching Waveforms



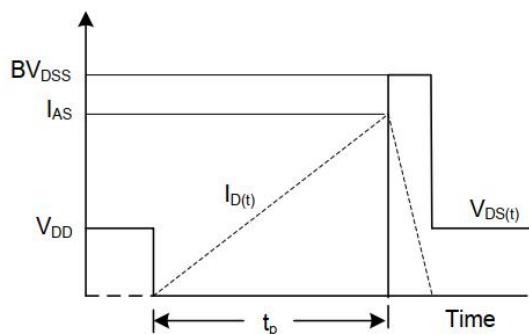
Gate Charge Test Circuit



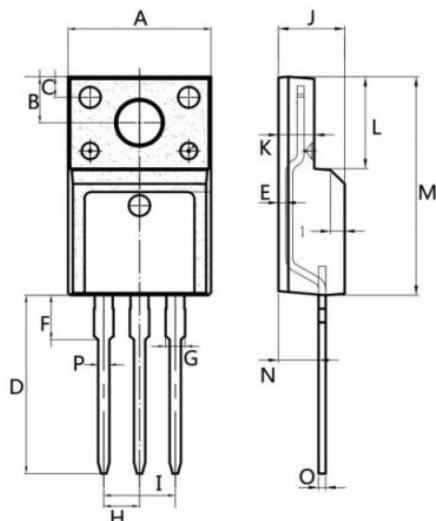
Gate Charge Waveform



Unclamped Inductive Switching Test Circuit

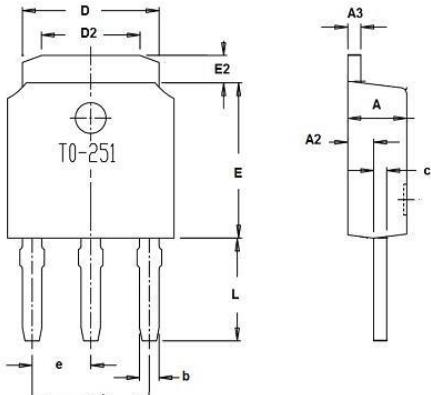


Unclamped Inductive Switching Waveforms

PACKAGE MECHANICAL DATA (Unit: mm):
TO-220F


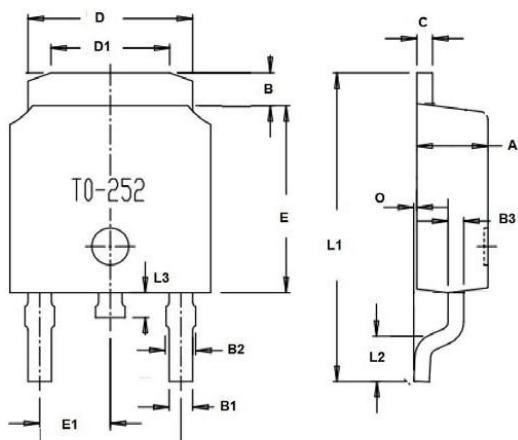
DIM	Min.	Max.
A	9.9	10.3
B	2.9	3.5
C	1.15	1.45
D	12.75	13.45
E	0.55	0.75
F	3.1	3.5
G	1.25	1.45
H	Typ 2.54	
I	Typ 5.08	
J	4.55	4.75
K	2.4	2.7
L	6.35	6.75
M	15.0	16.0
N	2.75	3.15
O	0.45	0.60
P	0.7	0.9

All Dimensions in millimeter

TO-251


DIM	Min.	Max.
A	2.1	2.5
A2	0.9	1..1
A3	Typ 0.5	
b	0.74	0.86
c	0.9	1.1
D	5.33	5.53
D2	3.65	4.05
E	6.0	6.2
E2	0.91	1.36
e	Typ 2.3	
e1	Typ 4.6	
L	3.7	4.3

All Dimensions in millimeter

TO-252


DIM	Min.	Max.
A	2.1	2.5
B	0.95	1.55
C	0.4	0.6
D	6.4	6.7
D1	5.1	5.8
E	5.8	6.4
E1	Typ 2.3	
E2	Typ 4.6	
B1	0.6	0.8
B2	0.75	0.95
O	--	0.15
L1	9.0	11.0
L2	1.3	1.7
L3	0.7	0.95

All Dimensions in millimeter

Statement:

- ◆ We reserve the right to change the manual without prior notice! Customers should obtain the latest version of the information before placing an order, and verify that the relevant information is complete and up-to-date.
- ◆ Any semiconductor product has the possibility of failure or failure under specific conditions. The buyer has the responsibility to comply with safety standards and take safety measures when using Silan product for system design and complete machine manufacturing, so as to avoid the occurrence of personal injury or property loss caused by potential failure risk!
- ◆ Product promotion will never end, our company will wholeheartedly provide customers with more excellent products!